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**Prepreg for laminate formation for printed circuit for high migration resistance - comprises glass cloth comprising glass fibres with low coefft of thermal expansion and high coating build-up of silane finishing agent with polyepoxy resin**

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#### Patent Family

| Patent Number | Kind | Date     | Application Number | Kind | Date     | Week   | Type |
|---------------|------|----------|--------------------|------|----------|--------|------|
| JP 8092394    | A    | 19960409 | JP 94231897        | A    | 19940927 | 199624 | B    |

**Priority Applications (Number Kind Date):** JP 94231897 A ( 19940927)

#### Patent Details

| Patent     | Kind | Language | Page | Main IPC    | Filing Notes |
|------------|------|----------|------|-------------|--------------|
| JP 8092394 | A    |          | 6    | C08J-005/24 |              |

#### Abstract:

JP 8092394 A

A prepreg (I) is prepd. by impregnating the base material of glass cloth with a thermoset resin followed by drying. The glass cloth comprises glass fibres which have a coefft of thermal expansion of less than 4 ppm/deg. C and the coating build-up of a finishing agent on them of more than 0.15 wt. %, pref. more than 0.2 wt.%, to intensify the affinity with the thermoset resin. Also claimed is a laminate (II) prepd. from (I).

USE - (II) is used for printed circuit laminates.

ADVANTAGE - (II) has a low coefft. of thermal expansion and a high migration resistance.

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